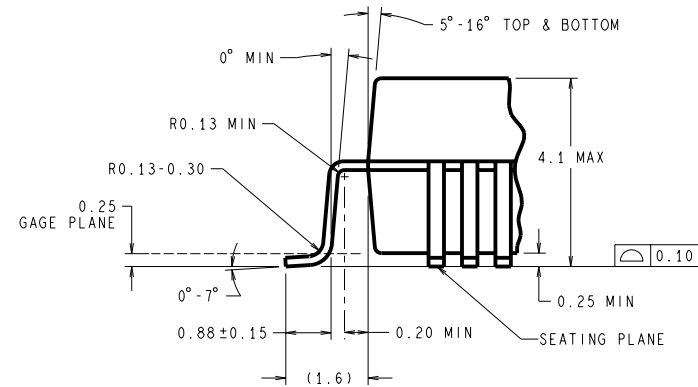
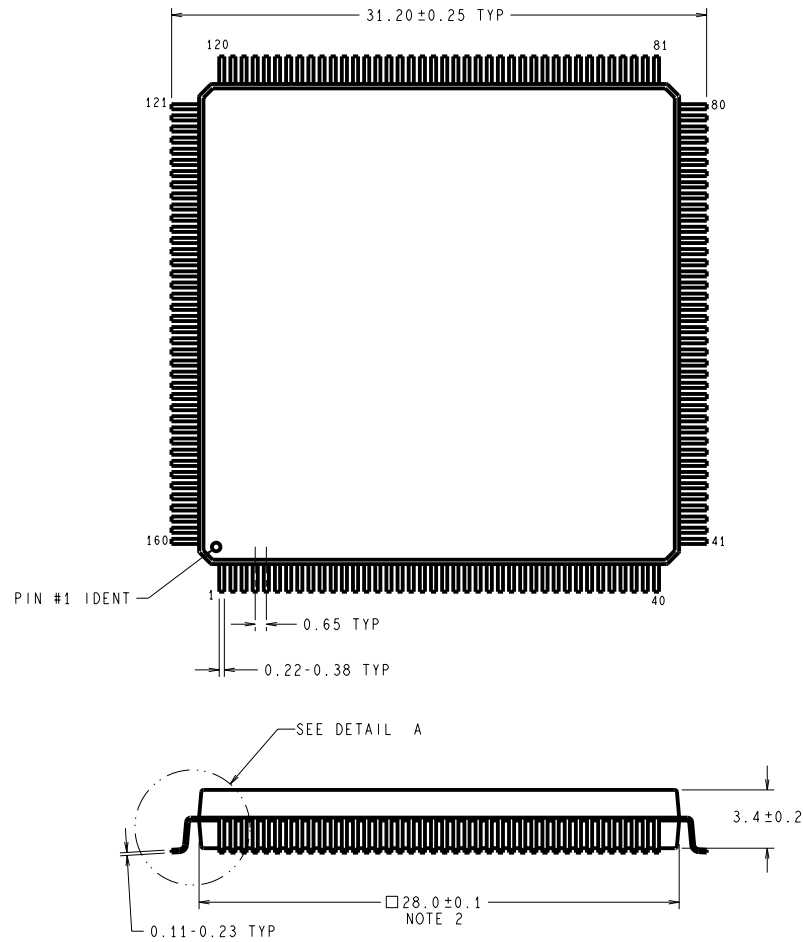


REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL.	09264	08/06/92	TL/HJK
B	REVISE NOTE 3 & DETAIL A.	09959	09/09/93	TL/HJK
C	REVISE & REDRAW PER JEDEC MS-022.	11038	07/10/95	DEG/



DETAIL A
TYP, SCALE: 15X

DIMENSIONS ARE IN MILLIMETERS

NOTES: UNLESS OTHERWISE SPECIFIED

- STANDARD LEAD FINISH:
7.62 MICROMETERS MINIMUM SOLDER PLATING (85/15)
THICKNESS ON COPPER.
- DIMENSION DOES NOT INCLUDE MOLD PROTRUSION.
MAXIMUM ALLOWABLE MOLD PROTRUSION 0.25mm PER SIDE.
- REFERENCE JEDEC STANDARD MS-022, VARIATION DD-1,
DATED FEB/95.

APPROVALS		DATE	National Semiconductor		
DRAWN	<i>D. E. Grady</i>	07/10/95	2900 Semiconductor dr., Santa Clara, CA 95052-8090		
DFTG. CHK.			POFP, JEDEC METRIC, 28 X 28 X 3.4mm, 160 LEAD		
ENGR. CHK.					
		SCALE	SIZE	DRAWING NUMBER	REV
		N/A	C	MKT-VUL160A	C
		DO NOT SCALE DRAWING			SHEET 1 of 1